

**IN THE SPECIFICATION:**

Please add the following new paragraph:

[0022] FIGs. 7-12 are plan views of the exemplary sputtering system target of FIG. 5 according to the present invention.

Please replace paragraph [0025] with the following amended paragraph:

--Although the electromagnets 503 are shown in FIG. 6 to have a specific geometrical arrangement, other geometrical arrangements, such as triangular, pentagonal, and hexagonal array patterns, may be applicable based upon desired deposition of materials. Exemplary different geometrical arrangement patterns are shown in FIGs. 7-12. For example, electromagnets disposed around an outer perimeter of the fixed plate may have a first matrix row/column arrangement and electromagnets disposed within a center portion of the fixed plate may have a second non-matrix arrangement such as a circular arrangement, for example, and both the first and second arrangements may be individually controlled.--